



HSEC8-DV SERIES

VERTICAL EDGE RATE® CARD SOCKET



EDGE
RATE
CONTACT

-DV to ECDP

*Performance data includes effects of a non-optimized PCB.
 **Test board losses de-embedded from performance data.
 Complete test data available at www.samtec.com?HSEC8-DV
 or contact sig@samtec.com

Three cross-sectional diagrams of BGA packages showing different solder joint configurations:

- RA to -DV**: Shows a package with a raised area (RA) on the left and a dip (DV) on the right, connected by a solder joint.
- DV to -DV**: Shows two packages, each with a dip (DV), connected by a solder joint.
- PCB to -DV**: Shows a package with a dip (DV) connected to a printed circuit board (PCB) by a solder joint.



Finalinch®
CERTIFIED | 28+ Gbps

UL
FILE NO. E111594

CSA
FILE NO. 000921 0 000

CABLE	CONNECTOR
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

Some lengths, styles and options are non-standard, non-returnable.

HSEC8 — **1** **POSITIONS**
PER ROW — **CARD**
THICKNESS — **PLATING**
OPTION — **DV** — **A** — **OTHER**
OPTION

-TR
=Tape & Reel
(09 - 70 only)

POSITIONS PER ROW	A	B
09†	(4.50) .177	(11.80) .465
13†	(6.10) .240	(15.00) .591
25†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.44
49†	(22.90) .902	(43.80) 1.72
50	(22.90) .902	(44.60) 1.75
60	(26.90) 1.059	(52.60) 2.07
70†	(26.90) 1.059	(60.60) 2.38
80†	(26.90) 1.059	(68.60) 2.70
100†	(26.90) 1.059	(84.60) 3.33

Positions where no dimensions are given do not have keying feature.

* Mates with ECDP Series.

† Available with -01 Card Only.

